

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-23 (canceled)

Claim 24 (currently amended): A device transfer method comprising the steps of:
embedding devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate; and

stripping the devices from the first substrate so as to hold the devices in an embedded state in the pressure sensitive adhesive layer, wherein the pressure sensitive adhesive layer is formed of an insulating material.

Claim 25 (previously presented): The device transfer method as set forth in claim 24, comprising hardening the pressure sensitive adhesive layer after the devices are held in the embedded state in the pressure sensitive adhesive layer.

Claim 26 (previously presented): The device transfer method as set forth in claim 25, comprising forming first electric wirings on the pressure sensitive adhesive layer after the pressure sensitive adhesive layer is hardened.

Claim 27 (previously presented): The device transfer method as set forth in claim 26, comprising adhering a third substrate onto the side on which the first electric wirings are formed of the pressure sensitive adhesive layer after the first electric wirings are formed on the pressure sensitive adhesive layer.

Claim 28 (previously presented): The device transfer method as set forth in claim 27, comprising stripping the second substrate and the pressure sensitive adhesive layer from each

other after the third substrate is adhered to the side on which the first electric wirings are formed of the pressure sensitive adhesive layer.

Claim 29 (previously presented): The device transfer method as set forth in claim 28, wherein the pressure sensitive adhesive layer is provided with openings reaching the devices after the second substrate and the pressure sensitive adhesive layer are stripped from each other.

Claim 30 (previously presented): The device transfer method as set forth in claim 29, comprising filling the openings with a conductive material and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 31 (previously presented): The device transfer method as set forth in claim 24, further comprising bringing the devices into contact with a temporary adhesion layer provided on the first substrate for temporarily adhering the devices to the temporary adhesion layer thereby arranging the devices on the first substrate, before the embedding of the devices into the pressure sensitive adhesive layer.

Claim 32 (previously presented): The device transfer method as set forth in claim 31, wherein a tack of the pressure sensitive adhesive layer provided on the second substrate is greater than a tack of the temporary adhesion layer provided on the first substrate.

Claim 33 (previously presented): The device transfer method as set forth in claim 32, wherein the tack any one of the pressure sensitive adhesive layer and the temporary adhesion layer is changed so that the tack of the pressure sensitive adhesive layer will be greater than the tack of the temporary adhesion layer.

Claim 34 (currently amended): The device transfer method as set forth in claim 24, wherein the embedding into the pressure sensitive adhesive layer provides the devices in a ~~partially~~partly embedded state.

Claim 35 (canceled)

Claim 36 (previously presented): A device transfer method comprising:

embedding other-side devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate where one-side devices are embedded in the pressure sensitive adhesive layer; and

stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded states in the pressure sensitive adhesive layer.

Claim 37 (previously presented): The device transfer method as set forth in claim 36, wherein the one-side devices and the other-side devices have different characteristics.

Claim 38 (previously presented): The device transfer method as set forth in claim 36, wherein the one-side devices and the other-side devices are held in the embedded state in different areas on the substrate.

Claim 39 (previously presented): A display apparatus obtained by a method comprising:

embedding devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate;

stripping the devices from the first substrate thereby holding the devices in an embedded state in the pressure sensitive adhesive layer, and hardening the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto a side on which the first electric wirings are formed of the pressure sensitive adhesive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 40 (previously presented): The display apparatus as set forth in claim 39, wherein display is carried out through simple matrix driving by impressing a voltage on the devices through the first electric wirings and the second electric wirings.

Claim 41 (previously presented): A display apparatus obtained by a method comprising:

embedding one-side devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate, and stripping the one-side devices from the first substrate thereby holding the one-side devices in an embedded state in the pressure sensitive adhesive layer;

further embedding other-side devices arranged on the first substrate into the pressure sensitive adhesive layer, and stripping the other-side devices from the first substrate thereby holding the other-side devices in an embedded state in the pressure sensitive adhesive layer, where the one-side devices are embedded in the pressure sensitive adhesive layer;

hardening the pressure sensitive adhesive layer where the one-side devices and the other-side devices are held in the embedded state in the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto the side on which the first electric wirings are formed of the pressure sensitive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the one-side devices or the other-side devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 42 (previously presented): The display apparatus as set forth in claim 41, wherein the one-side devices and the other-side devices have different characteristics.

Claim 43 (previously presented): The display apparatus as set forth in claim 41, wherein the one-side devices and the other-side devices are held in the embedded state in different areas on the second substrate.

Claim 44 (previously presented): The display apparatus as set forth in claim 41, wherein display is carried out through simple matrix driving by impressing a voltage on the one-side devices or the other-side devices through the first electric wirings and the second electric wirings.

Claim 45 (previously presented): The display apparatus as set forth in claim 41, wherein any one of the one-side devices and the other-side devices are any one of display devices and driving circuit devices.

Claim 46 (previously presented): The display apparatus as set forth in claim 45, wherein display is carried out through active matrix driving by impressing a voltage on the display devices by the driving circuit devices.